

## CLAIMS

I claim:

- 5        1.        A method of making a memory card card, comprising the steps of:  
             adding circuit elements to a circuit board, said circuit board includes a set of test  
             terminals;  
             testing one or more of said circuit elements using said test terminals; and  
             covering said test terminals with a conformal contact coating in order to prevent  
10        access to said test terminals.
2.        A method according to claim 1, wherein:  
             said step of covering includes applying a liquid directly to a first surface of said  
             circuit board.
- 15        3.        A method according to claim 2, wherein:  
             said liquid includes a solder mask.
4.        A method according to claim 2, wherein:  
20        said liquid includes a photoresist.
5.        A method according to claim 2, wherein:  
             said liquid includes a thermoplastic.
- 25        6.        A method according to claim 2, wherein:  
             said liquid includes an epoxy.

7. A method according to claim 2, wherein:  
said liquid includes polyimide.

5 8. A method according to claim 2, wherein:  
said liquid is applied using a screen printing process.

9. A method according to claim 1, wherein:  
said step of covering includes applying a film directly to a first surface of said  
circuit board.

10 10. A method according to claim 9, wherein:  
said film includes an adhesive on one surface.

15 11. A method according to claim 9, wherein:  
said film includes mylar.

12. A method according to claim 9, wherein:  
said film includes polyimide.

20 13. A method according to claim 1, wherein:  
said step of adding circuit elements includes adding a flash memory array to said  
circuit board.

25 14. A method according to claim 1, wherein:  
said step of adding circuit elements includes mounting a first die on said circuit  
board and mounting a second die on said first die.

15. A method according to claim 14, wherein:  
said first die includes a flash memory array and said second die includes a  
controller.

5 16. A method according to claim 14, wherein:  
said first die is wire bonded to said circuit board; and  
said second die is wire bonded to said circuit board.

10 17. A method according to claim 1, wherein:  
said circuit board includes a conductive layer and a first portion of said  
conductive layer forms said test terminals.

15 18. A method according to claim 17, wherein:  
a second portion of said conductive layer forms user terminals;  
said user terminals are positioned on an outside surface of said memory card; and  
said user terminals are in communication with at least a subset of said circuit  
elements.

20 19. A method according to claim 1, wherein:  
said step of adding circuit elements includes performing a transfer mold process  
to encapsulate said circuit elements without covering said test terminals.

25 20. A method according to claim 1, wherein:  
said step of covering is performed after said circuit board is removed from a strip  
of circuit boards.

21. A method according to claim 1, wherein:

said step of covering is performed before said circuit board is removed from a strip of circuit boards.

5           22.     A method according to claim 1, wherein:  
said memory card is a flash memory card.

          23.     A method according to claim 22, wherein:  
said step of covering includes applying a liquid directly to a first surface of said circuit board.

10           24.     A method according to claim 22, wherein:  
said step of covering includes applying a film directly to a first surface of said circuit board.

15           25.     A method of making a peripheral card, comprising the steps of:  
adding circuit elements to a plurality of circuit boards of a strip of circuit boards,  
each of said plurality of circuit boards includes a set of test terminals;  
separating said connected circuit boards;  
testing said circuit elements of said circuit boards using said test terminals; and  
20           applying a conformal contact coating on a first surface of each of said circuit  
boards to cover said test terminals and prevent access to said test terminals such that a  
particular circuit board has its test terminals covered after said particular circuit board has  
been tested.

25           26.     A method according to claim 25, wherein:  
said step of separating is performed after said step of applying.

27. A method according to claim 25, wherein:  
said step of separating is performed prior to said step of applying.

28. A method according to claim 25, wherein:  
5 said step of applying includes applying a liquid directly to a first surface of said circuit boards.

29. A method according to claim 25, wherein:  
said step of applying includes applying a film directly to a first surface of said  
10 circuit boards.

30. A method according to claim 25, wherein:  
said step of adding circuit elements includes mounting a first die on a first circuit  
board and mounting a second die on said first die;  
15 said first die includes a flash memory array and said second die includes a controller;  
said first die is wire bonded to said first circuit board; and  
said second die is wire bonded to said first circuit board.

20 31. A method according to claim 25, wherein:  
said peripheral card is a memory card.

32. A peripheral card manufactured according to a process comprising the  
steps of:  
25 adding circuit elements to a circuit board, said circuit board includes a set of test terminals;  
testing one or more of said circuit elements using said test terminals; and

applying a conformal contact coating on a first surface of said circuit board to cover said test terminals and prevent access to said test terminals.

33. A peripheral card according to claim 32, wherein:  
5 said step of applying includes applying a liquid directly to a first surface of said circuit board.

34. A peripheral card according to claim 32, wherein:  
said step of applying includes applying a film directly to a first surface of said  
10 circuit board.

35. A peripheral card according to claim 32, wherein:  
said circuit board includes a first die mounted on said circuit board and a second  
die mounted on said first die;  
15 said first die includes a flash memory array and said second die includes a controller;  
said first die is wire bonded to said circuit board; and  
said second die is wire bonded to said circuit board.

20 36. A peripheral card according to claim 32, wherein:  
said circuit board includes a conductive layer;  
a first portion of said conductive layer forms said test terminals;  
a second portion of said conductive layer forms user terminals;  
said user terminals are positioned on an outside surface of said peripheral card;  
25 and

said circuit elements are encapsulated by a transfer mold process without covering

said test terminals.

37. A peripheral card according to claim 32, wherein:  
said peripheral card is a memory card.

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38. A peripheral card, comprising:  
a circuit board;  
circuit elements on said circuit board;  
a set of user terminals on said circuit board, said user terminals are in  
10 communication with at least a subset of said circuit elements;  
a set of test terminals on said circuit board, said test terminals are in  
communication with one or more of said circuit elements;  
an enclosure that covers a portion of said circuit board and said circuit elements  
without covering said set of user terminals and said set of test terminals; and  
15 a conformal contact coating on a first surface of said circuit board covering said  
test terminals and preventing access to said test terminals.

39. A peripheral card according to claim 38, wherein:  
said conformal contact coating is applied as a liquid directly to said first surface  
20 of said circuit board.

40. A peripheral card according to claim 38, wherein:  
said conformal contact coating includes a film that is applied directly to said first  
surface of said circuit board.

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41. A peripheral card according to claim 38, wherein:  
said circuit elements board include a first die mounted on said circuit board and a

second die mounted on said first die.

5           42.     A peripheral card according to claim 41, wherein:  
              said first die is wire bonded to said circuit board; and  
              said second die is wire bonded to said circuit board.

              43.     A peripheral card according to claim 42, wherein:  
              said first die includes a flash memory array and said second die includes a  
10           controller.

              44.     A peripheral card according to claim 41, wherein:  
              said first die includes a flash memory array and said second die includes a  
15           controller.

              45.     A peripheral card according to claim 38, wherein:  
              said circuit board includes a conductive layer;  
              a first portion of said conductive layer forms said test terminals;  
              a second portion of said conductive layer forms said user terminals; and  
              said user terminals are positioned on an outside surface of said peripheral card.  
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              46.     A peripheral card according to claim 38, wherein:  
              said peripheral card is a memory card.

              47.     A method performed for a peripheral card, comprising the steps of:  
25           testing one or more circuit elements of a first peripheral card using one or more  
              test terminals of said first peripheral card; and  
              covering said test terminals with a conformal contact coating in order to prevent



access to said test terminals.

48. A method according to claim 47, wherein:  
said step of covering includes applying a liquid directly to said first peripheral  
5 card.

49. A method according to claim 47, wherein:  
said step of covering includes applying a film directly to said first peripheral card.

10 50. A method according to claim 47, wherein:  
said circuit elements include a flash memory array.

51. A method according to claim 47, wherein:  
said first peripheral card is a memory card.

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